

Part Number: XZFBB56WT-5

3.0x1.0 mm SMD CHIP LED LAMP

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Features

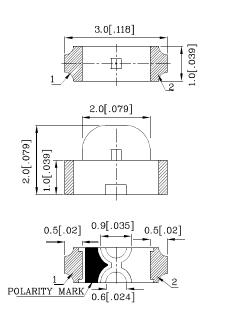
- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- \bullet Tinned pads for improved solderability
- Package : 2000pcs / reel
- Moisture sensitivity level : level 3
- \bullet RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics



Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		FBB (InGaN)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA	
Power Dissipation	\mathbf{P}_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C	
Storage Temperature	Tstg	$-40 \sim +85$		
Electrostatic Discharge Threshold (HBM)		250	V	

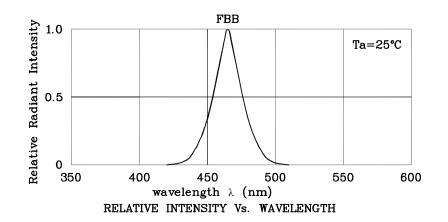
Operating Characteristics (T _A =25°C)		FBB (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	3.3	V
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	4	V
Reverse Current (Max.) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	465	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	$_{\rm pF}$

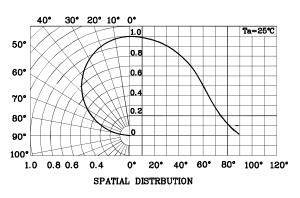
Number Color	Emitting Material	Lens-color	(I _F =2)	· ·	nm λP	Viewing Angle 20 1/2
			min.	typ.		
XZFBB56WT-5 Blue	InGaN	Water Clear	100	198	465	120°

XDSB5713 V1 Layout: Maggie L.

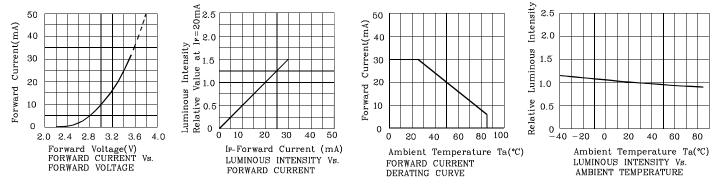
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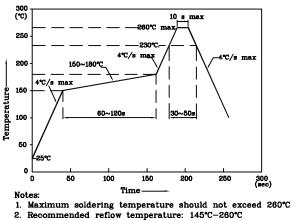


FBB



LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



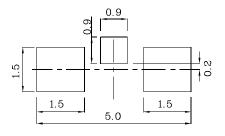
3. Do not put stress to the epoxy resin during

high temperatures conditions

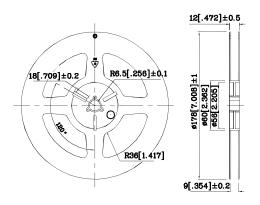


✤ The device has a single mounting surface. The device must be mounted according to the specifications.

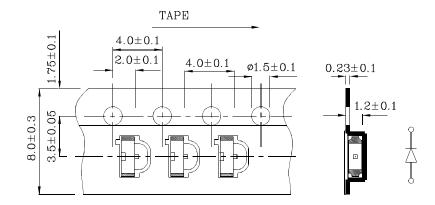
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V $\,$

Note: Accuracy may depend on the sorting parameters.

Mar 23,2011



PACKING & LABEL SPECIFICATIONS

